Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **INPUT**
2. **OUTPUT**
3. **OUTPUT**
4. **GND**

**.074”**

**.070”**

 **2 3**

**1**

 **4**

**05**

**MASK**

**ID**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: INPUT**

**Mask Ref: B16A**

**APPROVED BY: DK DIE SIZE .070” X .074” DATE: 11/8/22**

**MFG: MOTOROLA / ON SEMI THICKNESS .015” P/N: MCC7905AC**

**DG 10.1.2**

#### Rev B, 7/19/02